

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT2614644

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHIH-WEI WU</td> <td>09/23/2013</td> </tr> <tr> <td>YING-CHING SHIH</td> <td>09/23/2013</td> </tr> <tr> <td>SZU-WEI LU</td> <td>09/23/2013</td> </tr> <tr> <td>JING-CHENG LIN</td> <td>09/23/2013</td> </tr> </tbody> </table>		Name	Execution Date	CHIH-WEI WU	09/23/2013	YING-CHING SHIH	09/23/2013	SZU-WEI LU	09/23/2013	JING-CHENG LIN	09/23/2013
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YING-CHING SHIH	09/23/2013										
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JING-CHENG LIN	09/23/2013										
RECEIVING PARTY DATA											
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.										
Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK										
City:	HSINCHU										
State/Country:	TAIWAN										
Postal Code:	300										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14079736</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14079736						
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Application Number:	14079736										
CORRESPONDENCE DATA											
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Signature:	/Randy A. Noranbrock/
Date:	11/14/2013
Total Attachments: 1 source=EfiledAssgn#page1.tif	

### ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Chih-Wei WU
- 2) Ying-Ching SHIH
- 3) Szu-Wei LU
- 4) Jing-Cheng LIN

who has made a certain new and useful invention, hereby sells, assigns and transfers unto TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

#### STACKING OF MULTIPLE DIES FOR FORMING THREE DIMENSIONAL INTEGRATED CIRCUIT (3DIC) STRUCTURE

- (a) for which an application for United States Letters Patent was filed on 2013-11-14, and identified by United States Patent Application No. 14/079,736; or
- (b) for which an application for United States Letters Patent was executed on \_\_\_\_\_,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Chih-Wei Wu  
Name: Chih-Wei WU

2013/09/23  
Date:

2) Ying-Ching Shih  
Name: Ying-Ching SHIH

2013/09/23  
Date:

3) Szu-Wei Lu  
Name: Szu-Wei LU

2013/9/23  
Date:

4) Jing-Cheng Lin  
Name: Jing-Cheng LIN

2013/9/23  
Date: